



Cornell University



IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY

Flexible Electronics Symposium

The second annual **Flexible Electronics Symposium**, hosted by Binghamton University's Center for Advanced Microelectronics Manufacturing, (Camm), in conjunction with the IEEE Components, Packaging and Manufacturing Technology Society, Sandia National Laboratories and Cornell University, was held on August 19, 2009 in Binghamton, New York.

This workshop brought together over 120 leading researchers from academia, national labs, government and industry with the goal of developing collaborative partnerships on emerging flexible electronic technologies that will impact energy, environment, military and homeland security applications. Presentations were given in the fields of flexible electronics, functional printing, and emerging electronic materials. The workshop provided the opportunity for participants to review and share new research findings in critical technology areas and identify issues for the rapidly growing flexible electronics field. As part of the workshop, attendees toured the Center for Advanced Microelectronics Manufacturing (Camm), a national research lab focusing on roll-to-roll flexible electronics, and a networking dinner.

Speakers included: Bahgat Sammakia and James Turner, Binghamton University; David Gundlach, National Institutes for Standards and Technology; Changsoo Jang, University of Maryland, College Park; Dahwey Chu, Sandia National Laboratory; Kelly Lee and RJ Greco, Infotonics Technology Center; Christopher Ober, Cornell University; Charles Becker and Jeff Ash, General Electric; Minqian He, Corning Incorporated; and Fazila Seker, Xerox Research Center of Canada.

The workshop was held in conjunction with the Flex Tech Alliance's quarterly working group on Flexible, Printed and Organic Electronics.

The next symposium is scheduled for June, 2010.

Access Papers from Recent CPMT Conferences

You read, in the President's message (page 3), that he finds that conference papers are the critical links in our global knowledge supply chain. In CPMT-sponsored conferences, one regularly finds ideas for new innovations and interesting research results. Are you taking advantage of this "knowledge supply chain" to replenish your technical knowledge and discover where the technology is going? Here's your chance.

Here are the links to Proceedings and papers from the summer and fall CPMT Society conferences. Most researchers belong to companies or institutions that subscribe to the full IEEE collection. If your work/university domain isn't automatically recognized by your browser, please contact your librarian.

Electronic Components and Technology Conf, ECTC 2009.
59th - ieeexplore.ieee.org/servlet/opac?punumber=5066986

European Microelectronics and Packaging Conference, EMPC 2009. - ieeexplore.ieee.org/servlet/opac?punumber=5238690

Int'l Conf on Electronic Packaging Technology & High Density Packaging, 2009. ICEPT-HDP -
ieeexplore.ieee.org/servlet/opac?punumber=5234372

Signal Propagation on Interconnects, 2009. SPI. IEEE Workshop on - ieeexplore.ieee.org/servlet/opac?punumber=5073942

31st Int'l Spring Seminar on Electronics Technology, 2008. ISSE - ieeexplore.ieee.org/servlet/opac?punumber=5254892

55th IEEE Holm Conf on Electrical Contacts, 2009
- ieeexplore.ieee.org/servlet/opac?punumber=5284378

IEEE Int'l Conf on 3D System Integration, 2009. 3DIC
- ieeexplore.ieee.org/servlet/opac?punumber=5290624

Second Int'l Conf on Thermal Issues in Emerging Technologies, 2008. ThETA ieeexplore.ieee.org/servlet/opac?punumber=5159257

Scan through these Tables of Contents, and access the papers that are most meaningful to *your* career!